

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-9 (canceled)

Claim 10 (previously presented): A probe for probing test points on a target board, comprising:

a first printed circuit board (PCB) having a plurality of signal routes for routing signals to a test instrument;

a plurality of spring pins for probing the test points on the target board, each spring pin of which is i) disposed perpendicularly to the first PCB, and ii) electrically coupled to at least one signal route of the first PCB; and

a second PCB having a plurality of signal routes, wherein: i) at least some of the plurality of spring pins are electrically coupled to the signal routes of the second PCB such that their probe tips extend beyond a first edge of the second PCB; ii) the second PCB is abutted perpendicularly to the first PCB, with an edge of the second PCB opposite said first edge being abutted to the first PCB; and iii) the signal routes of the second PCB are electrically coupled to the signal routes of the first PCB.

Claim 11 (original): The probe of claim 10, wherein:

the first PCB comprises a plurality of bonding pads on one surface thereof, each of which is electrically coupled to one of the signal routes of the first PCB;

the second PCB comprises a plurality of edge pads abutting the first PCB, each of which is electrically coupled to one of the signal routes of the second PCB; and

corresponding ones of the bonding pads and edge pads are electrically coupled to each other.

Claim 12 (original): The probe of claim 11, wherein said edge pads comprise plated ends of said signal routes of the second PCB.

Claim 13 (original): The probe of claim 11, wherein said edge pads comprise an extended, bent surface pad of the second PCB.

Claim 14 (original): The probe of claim 11, wherein said edge pads comprise exposed vias of the second PCB.

Claim 15 (original): The probe of claim 11, wherein corresponding ones of the bonding pads and edge pads are electrically coupled via solder.

Claim 16 (original): The probe of claim 11, wherein corresponding ones of the bonding pads and edge pads are electrically coupled via wire solder legs.

Claim 17 (original): The probe of claim 10, wherein bodies of the plurality of spring pins are soldered to signal routes on opposite surfaces of the second PCB.

Claim 18 (original): The probe of claim 10, wherein said signal routes of the second PCB comprise tip-network components positioned adjacent said spring pins.

Claim 19 (original): The probe of claim 18, wherein said tip-network components comprise isolation resistors.

Claim 20 (original): A method for forming a probe, comprising:

forming a row of vias in a first PCB;
cutting said first PCB along said row of vias, thereby exposing cross-sections of said vias at a cut edge of said first PCB;

electrically coupling a plurality of spring pins to a plurality of signal routes of the first PCB, wherein said signal routes of the first PCB are electrically coupled to ones of said vias, and wherein said spring pins are electrically coupled to the first PCB such that their probe tips extend beyond an edge of said first PCB opposite said cut edge;

abutting said cut edge of said first PCB to a second PCB, and electrically coupling said signal routes of the first PCB to signal routes of the second PCB, by means of said via cross-sections, so that said first PCB extends perpendicularly from said second PCB.

Claim 21 (original): The method of claim 20, wherein ones of said via cross-sections are coupled to signal routes on first and second opposite sides of the first PCB, the method further comprising:

cutting said first PCB along said cut edge to form first and second sets of edge pads from said via cross-sections; and

electrically coupling said edge pads to said signal routes of the second PCB.

Claim 22 (original): A method for probing test points on a target board, comprising:

selecting a test probe comprising a plurality of spring pins that are arranged perpendicularly to a main body portion of the test probe, said main body portion comprising a first printed circuit board (PCB) to which the plurality of spring pins are electrically coupled;

moving the test probe over the target board to seat an alignment mechanism of the test probe to a corresponding alignment mechanism of the target board;

applying pressure to at least one of the i) test probe or ii) target board to cause the plurality of spring pins to engage the test points on the target board; and
routing signals from the test points to a test instrument via the test probe.

Claim 23 (original): The method of claim 22, further comprising, while applying said pressure, applying enough pressure to cause a securing mechanism of the test probe to engage a securing mechanism of the target board.

Claim 24 (original): The method of claim 22, wherein said moving comprises moving said first PCB along a path that is substantially parallel to said target board.

Claim 25 (original): The method of claim 22, wherein the spring pins of the selected test probe are electrically coupled to traces of a second PCB that is perpendicularly attached to the first PCB.